

Appl. No. : 10/692,952
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AMENDMENTS TO THE CLAIMS

Please cancel Claims 1-13, 22 and 23.

Please amend Claims 14-16, 19-21, 24 and 25.

1.-13. (Canceled)

14. (Currently amended) ~~The system of claim 13;~~ A system for avoiding formation of gas bubbles on a selected region of a surface of a workpiece in a process chamber as the workpiece surface is brought in contact with a process solution for an electrochemical process using the process solution, comprising:

a workpiece carrier to hold and move the workpiece; and

a solution shaper having at least one high flow section to direct a process solution flow towards the selected region of the workpiece surface for a predetermined time, the solution shaper being adapted to move to bring the high flow section under the selected region of the workpiece surface, the solution shaper comprising a first shaping member and a second shaping member, wherein the shaping members are plates that are moved towards each other to form the high flow ~~region-section~~ under the selected region of the workpiece.

15. (Currently amended) The system of claim 14, wherein the shaping members are moved away from each other after the predetermined time to remove the high flow ~~region-section~~ and to stop directing the process solution flow.

16. (Currently amended) The system of claim 14, wherein the high flow ~~region-section~~ is comprised of at least one flow opening.

17. (Original) The system of claim 16, wherein the shaping members include one or more openings that allow the process solution to flow towards the surface of the workpiece.

18. (Original) The system of claim 17, wherein the openings are smaller than the at least one flow opening.

19. (Currently amended) The system of claim 14, wherein the high flow ~~region-section~~ is comprised of a slit.

20. (Currently amended) ~~The system of claim 11;~~ A system for avoiding formation of gas bubbles on a selected region of a surface of a workpiece in a process chamber as the workpiece

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surface is brought in contact with a process solution for an electrochemical process using the process solution, comprising:

a workpiece carrier to hold and move the workpiece; and

a solution shaper having at least one high flow section to direct a process solution flow towards the selected region of the workpiece surface for a predetermined time, wherein the solution shaper is adapted to move to bring the high flow section under the selected region of the workpiece surface, ~~wherein-and~~ the solution shaper is a removable plate which is used during ~~the~~ bubble removal and is removed after ~~the~~ bubble removal.

21. (Currently amended) The system of claim 20, wherein the removable plate includes a plurality of flow openings in differing sizes, wherein large openings are grouped to form the high flow ~~region-section~~.

22.-23. (Canceled)

24. (Currently amended) The system of claim ~~11-20~~, wherein the selected region is a central region of the surface of the workpiece.

25. (Currently amended) The system of claim ~~11-20~~, wherein the workpiece is a semiconductor wafer.